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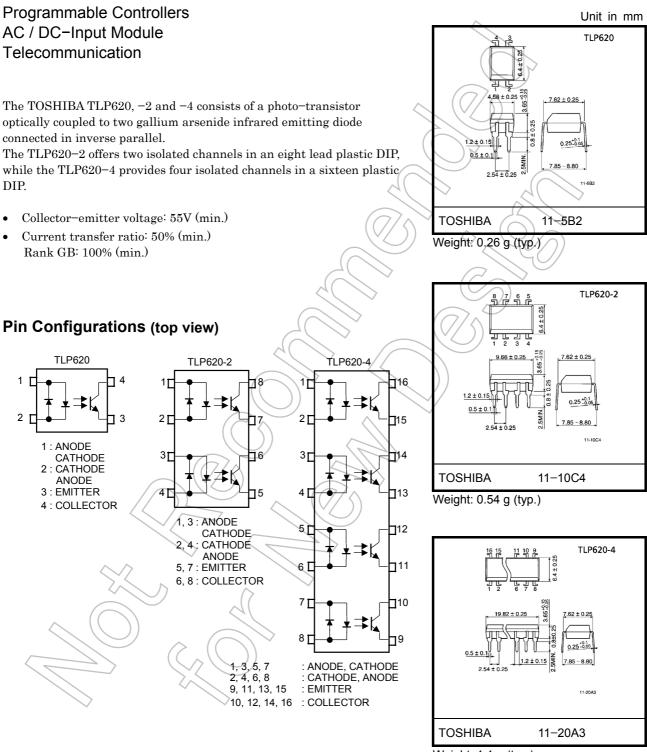
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TOSHIBA Photocoupler GaAs Ired & Photo-Transistor

TLP620, TLP620-2, TLP620-4



Weight: 1.1 g (typ.)

	Made In Japan	Made In Thailand			
UL recognized	E67349	*1	E152349	*1	
BSI approved	7426, 7427	*2	7426, 7427	*2	

*1 UL1577

- *2 BS EN60065: 2002, BS EN60950-1: 2002
- Isolation voltage: 5000V_{rms} (min.)
- Option (D4) type

VDE approved: DIN EN 60747-5-2, certificate no.40009302 Maximum operating insulation voltage: 890VPK Highest permissible over voltage: 8000VPK

(Note) When an EN 60747-5-2 approved type is needed, please designate the "Option(D4)".

• Creepage distance: 6.4mm (min.) Clearance: 6.4mm (min.) Insulation thickness: 0.4mm (min.)

Absolute Maximum Ratings (Ta = 25°C)

	Characteristic	Symbol	TLP620	TLP620-2 TLP620-4	Unit
	Forward current	I _F (RMS)	60	50	mA
	Forward current derating	ΔI _F / °C	–0.7 (Ta ≥ 39°C)	–0.5 (Ta ≥ 25°C)	mA / °C
D Pulse forward current		IFP	1 (100µs pulse, 100pps)		А
LED	Power dissipation (1 circuit)	PD	100	70	mW
	Power dissipation derating	APD / °C	-1.0	-0.7	mW / °C
	Junction temperature		12	5	°C
	Collector-emitter voltage	VCEO	55	5	V
	Emitter-collector voltage	V ECO	7		V
r	Collector current	Ic 🔿	50	0	mA
Detector	Collector power dissipation (1 circuit)	PG	150	100	mW
	Collector power dissipation derating (1 circuit) (Ta ≥ 25°C)	ΔP _C /°C	-1.5	-1.0	mW / °C
	Junction temperature	/")j	125		°C
Stor	rage temperature range	T _{stg}	-55~	125	°C
Оре	erating temperature range	Topr	-55~	100	°C
Lea	d soldering temperature	T _{sold}	260 (10s)	°C
Tota	al package power dissipation	Рт	250	150	mW
	al package power dissipation ating (Ta ≥ 25°C, 1 circuit)	ΔP _T /°C	-2.5	-1.5	mW / °C
Isol	ation voltage	BVS	5000 (AC, 1 mi	n., RH ≤ 60%)	V _{rms}

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Recommended Operating Conditions

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V _{CC}	_	5	24	V
Forward current	I _{F (RMS)}	—	16	20	mA
Collector current	IC	—	1	10	mA
Operating temperature	T _{opr}	-25		85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Individual Electrical Characteristics (Ta = 25°C)

-							
	Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
	Forward voltage	VF	I _F = ±10mA	1.0	1.15	> 1.3	V
LED	Forward current	١ _F	V _F = ±0.7V		2.5	20	μA
	Capacitance	CT	V = 0, f = 1MHz	\sim	60	_	pF
	Collector–emitter breakdown voltage	V _(BR) CEO	I _C ≠ 0.5mA	55	I	Ι	V
ctor	Emitter–collector breakdown voltage	V (BR) ECO	IE = 0.1mA	7	_	Ι	V
Detector	Collector dark current	20	V _{CE} = 24V	_	10	100	nA
		ICEO	V _{CE} = 24V, Ta = 85°C	—	2	50	μA
	Capacitance (collector to emitter)	C _{CE}	V _{CE} = 0, f = 1MHz	_	10	_	pF

Coupled Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Mln.	Тур.	Max.	Unit
Current transfer ratio		IF = ±5mA, V _{CE} = 5V	50	_	600	%
	IC / IF	Rank GB	100	_	600	70
Saturated CTR		IF = ±1mA, V _{CE} = 0.4V Rank GB	—	60	_	%
	I _C / I _F (sat)		30	—	_	
ZA N		1 _C = 2.4mA, I _F = ±8mA	-	—	0.4	
Collector-emitter saturation voltage	VCE (sat)	E (sat) $I_C = 0.2 \text{ mA}, I_F = \pm 1 \text{ mA}$ Rank GB	-	0.2	_	V
			—	—	0.4	
Off-state collector current	IC (off)	$V_{F} = \pm 0.7 V, V_{CE} = 24 V$	_	1	10	μA
CTR symmetry	IC (ratio)	$I_{C} (I_{F} = -5mA) / I_{C} (I_{F} = +5mA)$	0.33	1	3	_

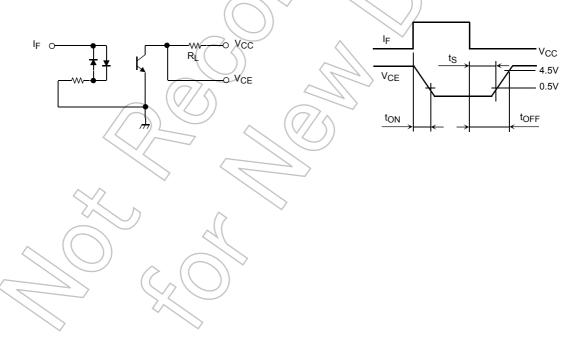
Isolation Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Capacitance input to output	CS	V _S = 0, f = 1MHz	_	0.8	_	pF
Isolation resistance	R _S	V _S = 500V	1×10 ¹²	10 ¹⁴		Ω
		AC, 1 minute	5000	-	_	V
Isolation voltage	BVS	AC, 1 second, in oil	(-)	10000	_	V _{rms}
		DC, 1 minute, in oil) /	10000	_	V _{dc}

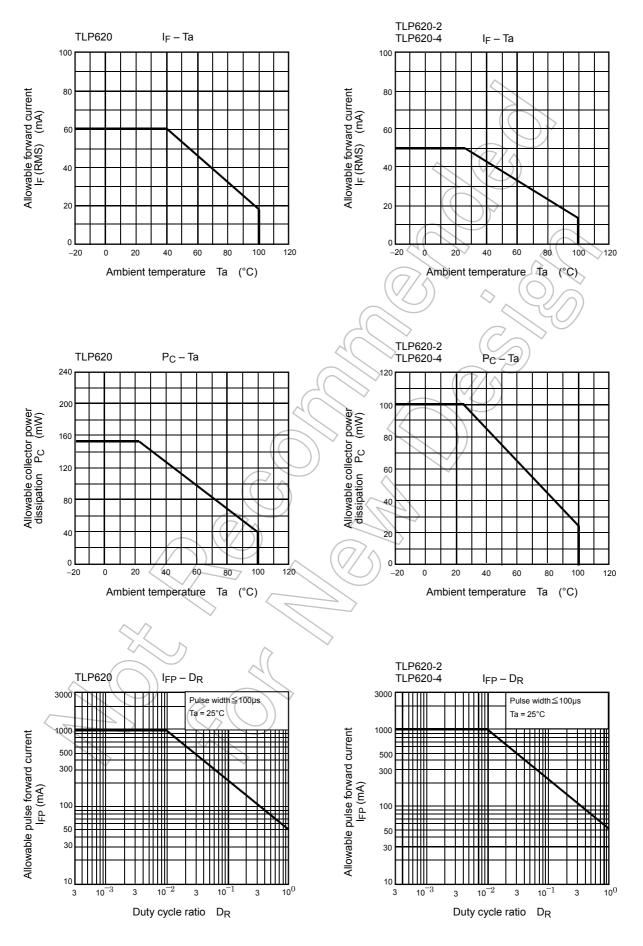
Switching Characteristics (Ta = 25°C)

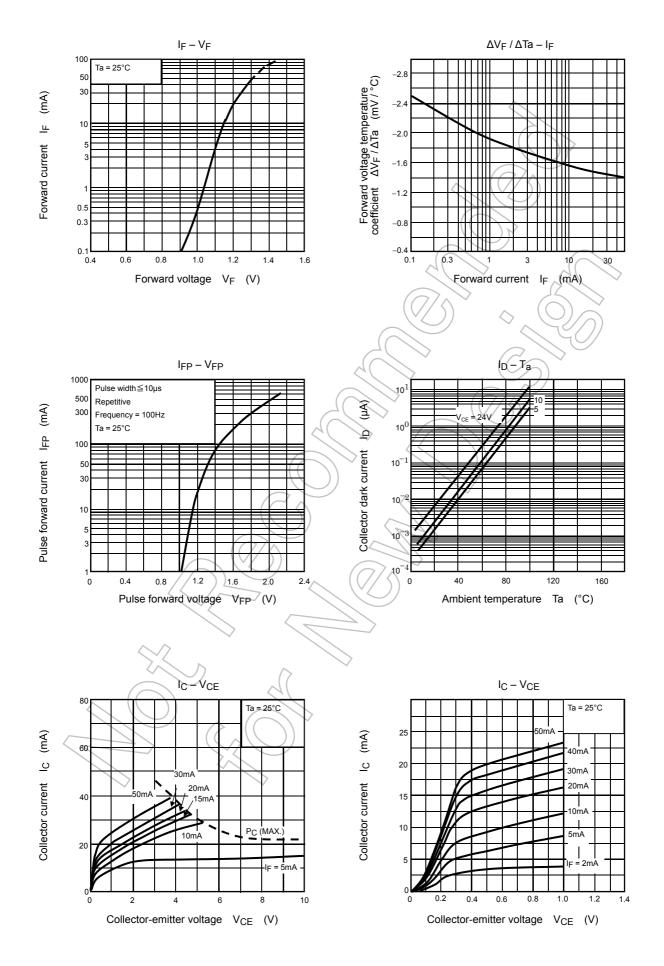
Characteristic	Symbol	Test Condition Min. Typ. Max. Unit
Rise time	tr	
Fall time	t _f	$V_{CC} = 10V \\ I_C = 2mA \\ R_L = 100\Omega $
Turn-on time	t _{on}	$I_{C} = 2mA$ $R_{L} = 100\Omega$ μs
Turn-off time	t _{off}	
Turn–on time	t _{ON}	- 2 -
Storage time	ts	$R_L = 1.9kΩ$ (Fig.1) - 15 - μs
Turn-off time	tOFF	- 25 -

Fig. 1 Switching time test circuit

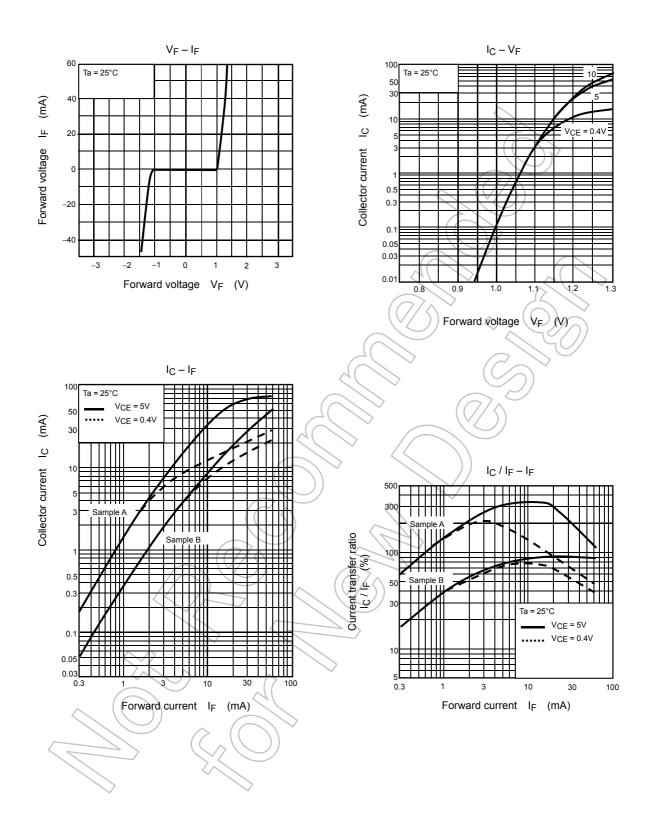


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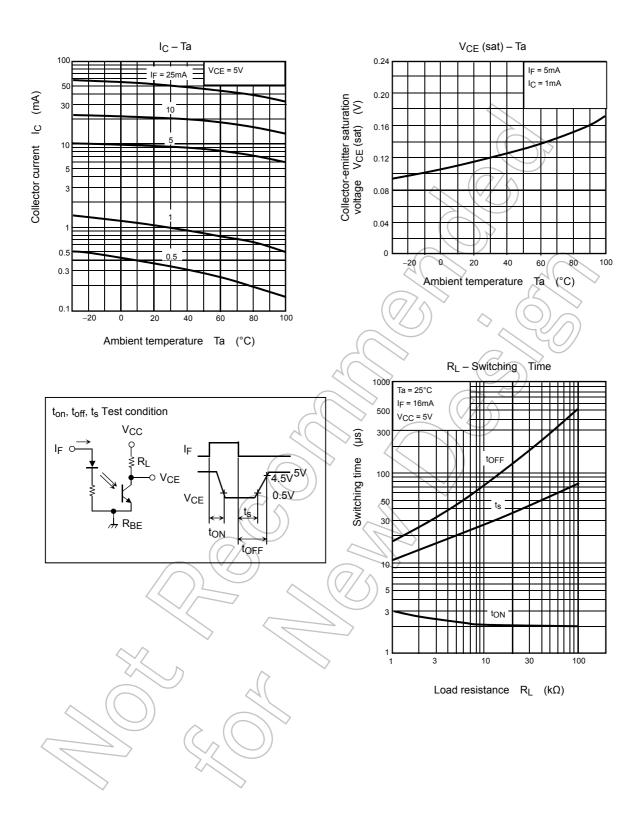




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